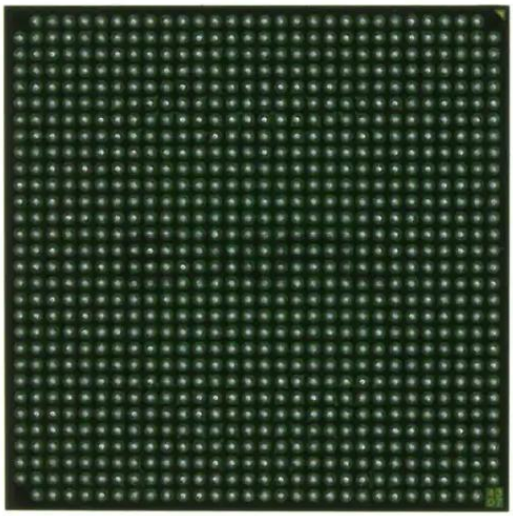

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2320
Number of Logic Elements/Cells	20880
Total RAM Bits	1622016
Number of I/O	556
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FCBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp20-6ff896i

  - HyperTransport (LDT) I/O with current driver buffers
  - Built-in DDR input and output registers
- Proprietary high-performance SelectLink technology for communications between Xilinx devices
  - High-bandwidth data path
  - Double Data Rate (DDR) link
  - Web-based HDL generation methodology
- SRAM-Based In-System Configuration
  - Fast SelectMAP™ configuration
  - Triple Data Encryption Standard (DES) security option (bitstream encryption)
  - IEEE 1532 support
  - Partial reconfiguration
  - Unlimited reprogrammability
  - Readback capability
- Supported by Xilinx Foundation™ and Alliance Series™ Development Systems
  - Integrated VHDL and Verilog design flows
  - ChipScope™ Integrated Logic Analyzer
- 0.13 µm Nine-Layer Copper Process with 90 nm High-Speed Transistors
- 1.5V (V_{CCINT}) core power supply, dedicated 2.5V V_{CCAUX} auxiliary and V_{CCO} I/O power supplies
- IEEE 1149.1 Compatible Boundary-Scan Logic Support
- Flip-Chip and Wire-Bond Ball Grid Array (BGA) Packages in Standard 1.00 mm Pitch.
- Wire-Bond BGA Devices Available in Pb-Free Packaging (**www.xilinx.com/pbfree)**
- Each Device 100% Factory Tested

General Description

The Virtex-II Pro and Virtex-II Pro X families contain platform FPGAs for designs that are based on IP cores and customized modules. The family incorporates multi-gigabit transceivers and PowerPC CPU blocks in Virtex-II Pro Series FPGA architecture. It empowers complete solutions for telecommunication, wireless, networking, video, and DSP applications.

The leading-edge 0.13 µm CMOS nine-layer copper process and Virtex-II Pro architecture are optimized for high performance designs in a wide range of densities. Combining a wide variety of flexible features and IP cores, the Virtex-II Pro family enhances programmable logic design capabilities and is a powerful alternative to mask-programmed gate arrays.

Architecture

Array Overview

Virtex-II Pro and Virtex-II Pro X devices are user-programmable gate arrays with various configurable elements and embedded blocks optimized for high-density and high-performance system designs. Virtex-II Pro devices implement the following functionality:

- Embedded high-speed serial transceivers enable data bit rate up to 3.125 Gb/s per channel (RocketIO) or 6.25 Gb/s (RocketIO X).
- Embedded IBM PowerPC 405 RISC processor blocks provide performance up to 400 MHz.
- SelectIO-Ultra blocks provide the interface between package pins and the internal configurable logic. Most popular and leading-edge I/O standards are supported by the programmable IOBs.
- Configurable Logic Blocks (CLBs) provide functional elements for combinatorial and synchronous logic, including basic storage elements. BUFTs (3-state buffers) associated with each CLB element drive dedicated segmentable horizontal routing resources.
- Block SelectRAM+ memory modules provide large 18 Kb storage elements of True Dual-Port RAM.
- Embedded multiplier blocks are 18-bit x 18-bit dedicated multipliers.
- Digital Clock Manager (DCM) blocks provide self-calibrating, fully digital solutions for clock distribution delay compensation, clock multiplication and division, and coarse- and fine-grained clock phase shifting.

A new generation of programmable routing resources called Active Interconnect Technology interconnects all these elements. The general routing matrix (GRM) is an array of routing switches. Each programmable element is tied to a switch matrix, allowing multiple connections to the general routing matrix. The overall programmable interconnection is hierarchical and supports high-speed designs.

All programmable elements, including the routing resources, are controlled by values stored in static memory cells. These values are loaded in the memory cells during configuration and can be reloaded to change the functions of the programmable elements.

Features

This section briefly describes Virtex-II Pro / Virtex-II Pro X features. For more details, refer to Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description.

RocketIO / RocketIO X MGT Cores

The RocketIO and RocketIO X Multi-Gigabit Transceivers are flexible parallel-to-serial and serial-to-parallel embedded transceiver cores used for high-bandwidth interconnection between buses, backplanes, or other subsystems.

Multiple user instantiations in an FPGA are possible, providing up to 100 Gb/s (RocketIO) or 170 Gb/s (RocketIO X) of full-duplex raw data transfer. Each channel can be operated at a maximum data transfer rate of 3.125 Gb/s (RocketIO) or 6.25 Gb/s (RocketIO X).

cation is given at the receiver interface. The realignment indicator is a distinct output.

The transceiver continuously monitors the data for the presence of the 10-bit character(s). Upon each occurrence of a 10-bit character, the data is checked for word alignment. If comma detect is disabled, the data is not aligned to any particular pattern. The programmable option allows a user to align data on comma+, comma–, both, or a unique user-defined and programmed sequence.

Comma detection has been expanded beyond 10-bit symbol detection and alignment to include 8-bit symbol detection and alignment for 16-, 20-, 32-, and 40-bit paths. The ability to detect symbols, and then either align to 1-word, 2-word, or 4-word boundaries is included. The RXSLIDE input allows the user to “slide” or “slip” the alignment by one bit in each 16-, 20-, 32- and 40-bit mode at any time for SONET applications. Comma detection can be bypassed when needed.

Clock Correction

RXRECCLK (the recovered clock) reflects the data rate of the incoming data. RXUSRCLK defines the rate at which the FPGA fabric consumes the data. Ideally, these rates are identical. However, since the clocks typically have different sources, one of the clocks will be faster than the other. The receiver buffer accommodates this difference between the clock rates. See Figure 6.

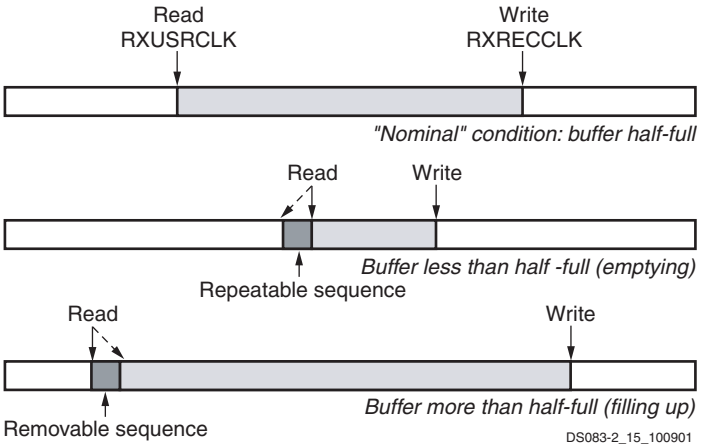

Figure 6: **Clock Correction in Receiver**

Nominally, the buffer is always half full. This is shown in the top buffer, Figure 6, where the shaded area represents buffered data not yet read. Received data is inserted via the write pointer under control of RXRECCLK. The FPGA fabric reads data via the read pointer under control of RXUSRCLK. The half full/half empty condition of the buffer gives a cushion for the differing clock rates. This operation continues indefinitely, regardless of whether or not "meaningful" data is being received. When there is no meaningful data to be received, the incoming data will consist of IDLE characters or other padding.

If RXUSRCLK is faster than RXRECCLK, the buffer becomes more empty over time. The clock correction logic corrects for this by decrementing the read pointer to reread a repeatable byte sequence. This is shown in the middle buffer, Figure 6, where the solid read pointer decrements to the value represented by the dashed pointer. By decrementing the read pointer instead of incrementing it in the usual fashion, the buffer is partially refilled. The transceiver design will repeat a single repeatable byte sequence when necessary to refill a buffer. If the byte sequence length is greater than one, and if attribute CLK_COR_REPEAT_WAIT is 0, then the transceiver may repeat the same sequence multiple times until the buffer is refilled to the desired extent.

Similarly, if RXUSRCLK is slower than RXRECCLK, the buffer will fill up over time. The clock correction logic corrects for this by incrementing the read pointer to skip over a removable byte sequence that need not appear in the final FPGA fabric byte stream. This is shown in the bottom buffer, Figure 6, where the solid read pointer increments to the value represented by the dashed pointer. This accelerates the emptying of the buffer, preventing its overflow. The transceiver design will skip a single byte sequence when necessary to partially empty a buffer. If attribute CLK_COR_REPEAT_WAIT is 0, the transceiver may also skip two consecutive removable byte sequences in one step to further empty the buffer when necessary.

These operations require the clock correction logic to recognize a byte sequence that can be freely repeated or omitted in the incoming data stream. This sequence is generally an IDLE sequence, or other sequence comprised of special values that occur in the gaps separating packets of meaningful data. These gaps are required to occur sufficiently often to facilitate the timely execution of clock correction.

Channel Bonding

Some gigabit I/O standards such as Infiniband specify the use of multiple transceivers in parallel for even higher data rates. Words of data are split into bytes, with each byte sent over a separate channel (transceiver). See Figure 7.

The top half of the figure shows the transmission of words split across four transceivers (channels or lanes). PPPP, QQQQ, RRRR, SSSS, and TTTT represent words sent over the four channels.

The bottom-left portion of Figure 7 shows the initial situation in the FPGA’s receivers at the other end of the four channels. Due to variations in transmission delay—especially if the channels are routed through repeaters—the FPGA fabric might not correctly assemble the bytes into complete words. The bottom-left illustration shows the incorrect assembly of data words PQPP, QRQQ, RSRR, and so forth.

To support correction of this misalignment, the data stream includes special byte sequences that define corresponding points in the several channels. In the bottom half of Figure 7, the shaded "P" bytes represent these special characters. Each receiver recognizes the "P" channel bond-

Virtex-II Pro Switching Characteristics

Switching characteristics are specified on a per-speed-grade basis and can be designated as Advance, Preliminary, or Production. Note that Virtex-II Pro Performance Characteristics are subject to these guidelines, as well. Each designation is defined as follows:

Advance: These speed files are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary: These speed files are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Production: These speed files are released once enough production silicon of a particular device family member has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

Since individual family members are produced at different times, the migration from one category to another depends completely on the status of the fabrication process for each device. Table 15 correlates the current status of each Virtex-II Pro device with a corresponding speed file designation.

All specifications are always representative of worst-case supply voltage and junction temperature conditions.

Table 15: **Virtex-II Pro Device Speed Grade Designations**

Device	Speed Grade Designations		
	Advance	Preliminary	Production
XC2VP2			-7, -6, -5
XC2VP4			-7, -6, -5
XC2VP7			-7, -6, -5
XC2VP20			-7, -6, -5
XC2VPX20		-6, -5	
XC2VP30			-7, -6, -5
XC2VP40			-7, -6, -5
XC2VP50			-7, -6, -5
XC2VP70			-7, -6, -5
XC2VPX70		-6, -5	
XC2VP100			-6, -5

Testing of Switching Characteristics

All devices are 100% functionally tested. Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer (TRCE in the Xilinx Development System) and back-annotate to the simulation net list. Unless otherwise noted, values apply to all Virtex-II Pro devices.

PowerPC Switching Characteristics

Table 16: **Processor Clocks Absolute AC Characteristics**

Description	Speed Grade						Units
	-7		-6		-5		
	Min	Max	Min	Max	Min	Max	
CPMC405CLOCK frequency	0	400(1)	0	350(1)	0	300	MHz
JTAGC405TCK frequency(2)	0	200	0	175	0	150	MHz
PLBCLK(3)	0	400	0	350	0	300	MHz
BRAMDSOCMCLK(3)	0	400	0	350	0	300	MHz
BRAMISOCMCLK(3)	0	400	0	350	0	300	MHz

Notes:

1. **IMPORTANT!** When CPMC405CLOCK runs at speeds greater than 350 MHz in -7 Commercial grade dual-processor devices, or greater than 300 MHz in -6 Industrial grade dual-processor devices, users must implement the technology presented in **XAPP755**, "PowerPC 405 Clock Macro for -7(C) and -6(I) Speed Grade Dual-Processor Devices." Refer to Table 1, Module 1 to identify dual-processor devices.
2. The theoretical maximum frequency of this clock is one-half the CPMC405CLOCK. However, the achievable maximum is dependent on the system, and will be much less.
3. The theoretical maximum frequency of these clocks is equal to the CPMC405CLOCK. However, the achievable maximum is dependent on the system. Please see ***PowerPC 405 Processor Block Reference Guide*** and **XAPP640** for more information.

Table 27: **RocketIO Transmitter Switching Characteristics**

Description	Symbol	Conditions	Min	Typ	Max	Units
Serial data rate, full-speed clock	F_{GTX}	Flipchip packages	1.0		3.125(1)	Gb/s
		Wirebond packages	1.0		2.5(1)	Gb/s
Serial data rate, half-speed clock(3) (2X oversampling)		Flipchip packages	0.600		1.0	Gb/s
		Wirebond packages	0.600		1.0	Gb/s
Serial data output deterministic jitter	T_{DJ}	2.126 Gb/s – 3.125 Gb/s			0.17	UI(2)
		1.0626 Gb/s – 2.125 Gb/s			0.08	UI
		1.0 Gb/s – 1.0625 Gb/s			0.05	UI
		600 Mb/s – 999 Mb/s			0.08(4)	UI
Serial data output random jitter	T_{RJ}	2.126 Gb/s – 3.125 Gb/s			0.18	UI
		1.0626 Gb/s – 2.125 Gb/s			0.19	UI
		1.0 Gb/s – 1.0625 Gb/s			0.18	UI
		600 Mb/s – 999 Mb/s			0.18(4)	UI
TX rise time	T_{RTX}	20% – 80%		120		ps
TX fall time	T_{FTX}			120		ps
Transmit latency(5)	T_{TXLAT}	Including CRC		14	17	TXUSR CLK cycles
		Excluding CRC		8	11	
TXUSRCLK duty cycle	T_{TXDC}		45	50	55	%
TXUSRCLK2 duty cycle	T_{TX2DC}		45	50	55	%

Notes:
1. Serial data rate in the -5 speed grade is limited to 2.0 Gb/s in both wirebond and flipchip packages.
2. UI = Unit Interval
3. For serial rates under 1 Gb/s, the 3X (or greater) oversampling techniques described in **XAPP572** are required to meet the transmit jitter and receive jitter tolerance specifications defined in this data sheet.
4. The oversampling techniques described in **XAPP572** are required to meet these specifications for serial rates less than 1 Gb/s.
5. Transmit latency delay TXDATA to TXP/TXN. Refer to ***RocketIO Transceiver User Guide*** for more information on calculating latency.

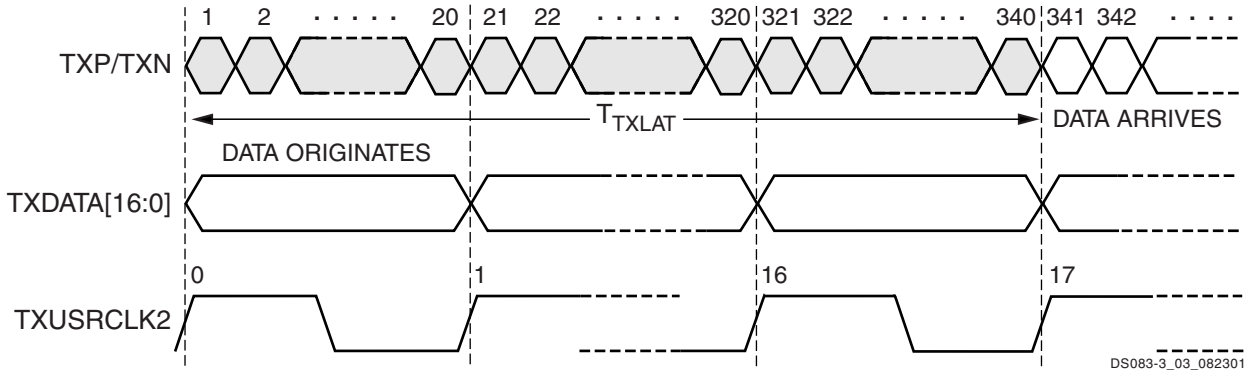

Figure 5: **RocketIO Transmit Latency (Maximum, Including CRC)**

Master/Slave Serial Mode Parameters

Clock timing for Slave Serial configuration programming is shown in Figure 8, with Master Serial clock timing shown in Figure 9. Programming parameters for both Slave and Master modes are given in Table 50.

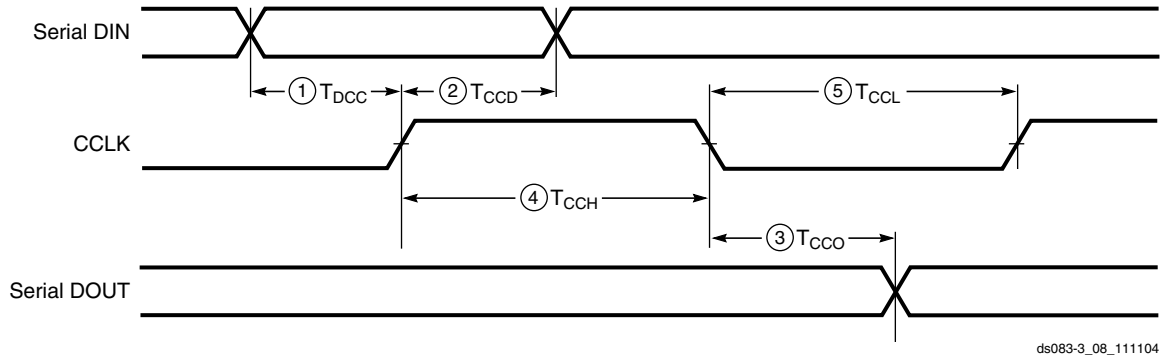

Figure 8: **Slave Serial Mode Timing Sequence**

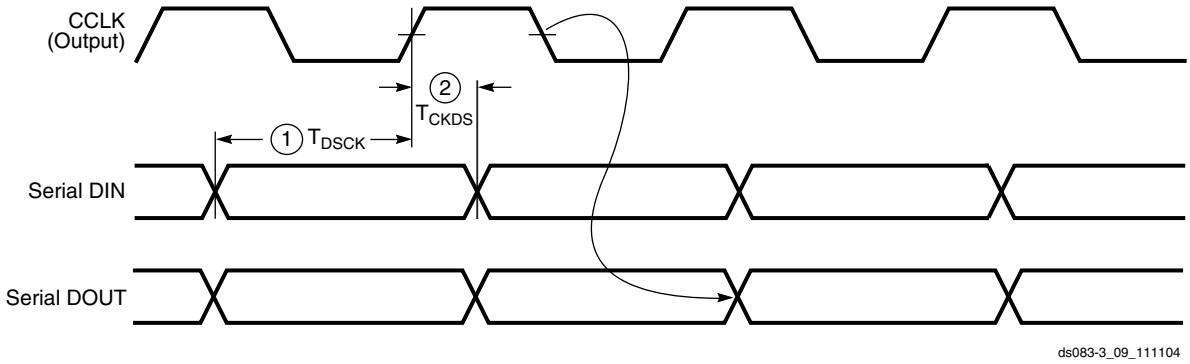

Figure 9: **Master Serial Mode Timing Sequence**

Table 50: **Master/Slave Serial Mode Timing Characteristics**

	Description	Figure References	Symbol	Value	Units
CCLK	DIN setup/hold, slave mode (Figure 8)	1/2	T_{DCC}/T_{CCD}	5.0/0.0	ns, min
	DIN setup/hold, master mode (Figure 9)	1/2	T_{DSCK}/T_{CKDS}	5.0/0.0	ns, min
	DOUT	3	T_{CCO}	12.0	ns, max
	High time	4	T_{CCH}	5.0	ns, min
	Low time	5	T_{CCL}	5.0	ns, min
	Maximum start-up frequency		$F_{CC\_STARTUP}$	50	MHz, max
	Maximum frequency		F_{CC_SERIAL}	66(1)	MHz, max
	Frequency tolerance, master mode with respect to nominal			+45% –30%	

Notes:
1. If no provision is made in the design to adjust the frequency of CCLK, F_{CC_SERIAL} should not exceed $F_{CC\_STARTUP}$.

Date	Version	Revision
08/25/03	2.9	• Updated time and frequency parameters as per speedsfile **v1.81**. • Table 1: Footnote (2) rewritten to specify “one or more banks.” • Table 2: Added footnote referring to XAPP659 for 3.3V I/O operation. • Table 53 and Table 54: Revised test setup footnote to refer to Figure 6. Previously specified a capacitive load parameter. • Table 57: Due to a document compilation error in v2.8, some DCM parameters were erroneously omitted from the full data sheet file (all four modules concatenated), though not from the stand-alone Module 3 file. The omitted parameters have been restored. • Table 64 and Table 66: Corrected parameters to expression in picoseconds, as labeled. Previously expressed in nanoseconds, but labeled picoseconds. • Figure 6: Added note to figure regarding termination resistors. • Table 5: Added $I_{CCINTMIN}$ for XC2VP30 device.
09/10/03	2.10	• Figure 7: Changed representation of mode pins M0, M1, and M2 indicating that they must be held to a constant DC level during and after configuration. • Table 49: Added footnote indicating that mode pins M0, M1, and M2 must be held to a constant DC level during and after configuration.
10/14/03	2.11	• Table 1: Deleted Footnote (2), which had derated the absolute maximum T_J when one or more banks operated at 3.3V. Changed T_J description from “Operating junction temperature” to “Maximum junction temperature”. Added new Footnote (2) linking to website for package thermal data. • Table 4 and Table 5: Filled in power-on and quiescent current parameters for all devices through XC2VP70. Added Industrial Grade multiplier specification to Footnote (1) in both tables. • In section General Power Supply Requirements, replaced reference to Answer Record 11713 with reference to **XAPP689** regarding handling of simultaneously switching outputs (SSO). • In section I/O Standard Adjustment Measurement Methodology: - Table 39 renamed Input Delay Measurement Methodology. Added footnotes. - Added new Table 40, Output Delay Measurement Methodology. - Replaced Figure 6, Generalized Test Setup, with new drawing. - Revised and extended text describing output delay measurement procedure. • Table 58: For Input Clock Low/High Pulse Width, PSCLK and CLKIN, changed existing Footnote (2) to new Footnote (3).
11/10/03	2.12	• Table 1: Changed 3.3V absolute max V_{IN} and V_{TS} from 3.75V to 4.05V. Added footnote referring to **XAPP659**. • Table 4: Removed MIN column from table.
12/05/03	3.0	• XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, updated and released to **Production status** as per speedsfile **v1.83**. Featured changes: - Speedsfile parameter values for -7 speed grade added for devices XC2VP2-XC2VP70. - Table 13 and Table 14: Pin-to-pin and register-to_register performance parameter values added. - Table 64: New parameter T_{DCD_LOCAL} (and footnote) replaces T_{DCD_CLK0}. - All remaining source-synchronous parameter values added (Table 64 & following).

FF672 Flip-Chip Fine-Pitch BGA Package

As shown in Table 8, XC2VP2, XC2VP4, and XC2VP7 Virtex-II Pro devices are available in the FF672 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for differences shown in the "No Connects" column. Following this table are the FF672 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
0	IO_L01N_0/VRP_0	B24			
0	IO_L01P_0/VRN_0	A24			
0	IO_L02N_0	D21			
0	IO_L02P_0	C21			
0	IO_L03N_0	E20			
0	IO_L03P_0/VREF_0	D20			
0	IO_L05_0/No_Pair	F19			
0	IO_L06N_0	E19			
0	IO_L06P_0	E18			
0	IO_L07N_0	D19			
0	IO_L07P_0	C19			
0	IO_L08N_0	B19			
0	IO_L08P_0	A19			
0	IO_L09N_0	G18			
0	IO_L09P_0/VREF_0	F18			
0	IO_L37N_0	D18	NC	NC	
0	IO_L37P_0	C18	NC	NC	
0	IO_L38N_0	G17	NC	NC	
0	IO_L38P_0	H16	NC	NC	
0	IO_L39N_0	F17	NC	NC	
0	IO_L39P_0	F16	NC	NC	
0	IO_L43N_0	E17	NC	NC	
0	IO_L43P_0	D17	NC	NC	
0	IO_L44N_0	G16	NC	NC	
0	IO_L44P_0	G15	NC	NC	
0	IO_L45N_0	E16	NC	NC	
0	IO_L45P_0/VREF_0	D16	NC	NC	
0	IO_L67N_0	F15			
0	IO_L67P_0	E15			
0	IO_L68N_0	D15			
0	IO_L68P_0	C15			
0	IO_L69N_0	H15			
0	IO_L69P_0/VREF_0	H14			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
7	IO_L36N_7		F27	NC		
7	IO_L35P_7		K24	NC		
7	IO_L35N_7		K23	NC		
7	IO_L34P_7		E30	NC		
7	IO_L34N_7/VREF_7		E29	NC		
7	IO_L33P_7		E28	NC		
7	IO_L33N_7		E27	NC		
7	IO_L32P_7		H26	NC		
7	IO_L32N_7		H25	NC		
7	IO_L31P_7		D30	NC		
7	IO_L31N_7		D29	NC		
7	IO_L06P_7		D28			
7	IO_L06N_7		C27			
7	IO_L05P_7		J24			
7	IO_L05N_7		J23			
7	IO_L04P_7		C30			
7	IO_L04N_7/VREF_7		C29			
7	IO_L03P_7		D26			
7	IO_L03N_7		C26			
7	IO_L02P_7		G26			
7	IO_L02N_7		G25			
7	IO_L01P_7/VRN_7		B28			
7	IO_L01N_7/VRP_7		A28			
0	VCCO_0		K21			
0	VCCO_0		K20			
0	VCCO_0		K19			
0	VCCO_0		K18			
0	VCCO_0		K17			
0	VCCO_0		K16			
0	VCCO_0		J21			
0	VCCO_0		J20			
0	VCCO_0		J19			
0	VCCO_0		J18			
1	VCCO_1		K15			
1	VCCO_1		K14			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	TXPPAD19		AK19			
N/A	TXNPAD19		AK20			
N/A	VTTXPAD19		AJ20			
N/A	AVCCAUXTX19		AJ19			
N/A	AVCCAUXRX21		AJ24			
N/A	VTRXPAD21		AJ25			
N/A	RXNPAD21		AK24			
N/A	RXPPAD21		AK25			
N/A	GNDA21		AH25			
N/A	TXPPAD21		AK26			
N/A	TXNPAD21		AK27			
N/A	VTTXPAD21		AJ27			
N/A	AVCCAUXTX21		AJ26			
N/A	VCCAUX		AK29			
N/A	VCCAUX		AK16			
N/A	VCCAUX		AK15			
N/A	VCCAUX		AK2			
N/A	VCCAUX		AJ30			
N/A	VCCAUX		AJ1			
N/A	VCCAUX		T30			
N/A	VCCAUX		T1			
N/A	VCCAUX		R30			
N/A	VCCAUX		R1			
N/A	VCCAUX		B30			
N/A	VCCAUX		B1			
N/A	VCCAUX		A29			
N/A	VCCAUX		A16			
N/A	VCCAUX		A15			
N/A	VCCAUX		A2			
N/A	VCCINT		Y19			
N/A	VCCINT		Y18			
N/A	VCCINT		Y17			
N/A	VCCINT		Y16			
N/A	VCCINT		Y15			
N/A	VCCINT		Y14			

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
7	IO_L43N_7	M31				
7	IO_L42P_7	L32				
7	IO_L42N_7	L31				
7	IO_L41P_7	N28				
7	IO_L41N_7	N27				
7	IO_L40P_7	M33				
7	IO_L40N_7/VREF_7	L33				
7	IO_L39P_7	M29				
7	IO_L39N_7	M28				
7	IO_L38P_7	N26				
7	IO_L38N_7	N25				
7	IO_L37P_7	L34				
7	IO_L37N_7	K34				
7	IO_L36P_7	L30				
7	IO_L36N_7	L29				
7	IO_L35P_7	L28				
7	IO_L35N_7	L27				
7	IO_L34P_7	K33				
7	IO_L34N_7/VREF_7	J33				
7	IO_L33P_7	K31				
7	IO_L33N_7	K30				
7	IO_L32P_7	M26				
7	IO_L32N_7	M25				
7	IO_L31P_7	H34				
7	IO_L31N_7	H33				
7	IO_L24P_7	H32	NC			
7	IO_L24N_7	H31	NC			
7	IO_L23P_7	K28	NC			
7	IO_L23N_7	K27	NC			
7	IO_L22P_7	J32	NC			
7	IO_L22N_7/VREF_7	J31	NC			
7	IO_L21P_7	J30	NC			
7	IO_L21N_7	J29	NC			
7	IO_L20P_7	G34	NC			
7	IO_L20N_7	G33	NC			
7	IO_L19P_7	H30	NC			
7	IO_L19N_7	H29	NC			
7	IO_L18P_7	L26	NC			

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
7	VCCO_7	T23				
7	VCCO_7	U23				
N/A	CCLK	AE9				
N/A	PROG_B	J26				
N/A	DONE	AE10				
N/A	M0	AF26				
N/A	M1	AE26				
N/A	M2	AE25				
N/A	TCK	J9				
N/A	TDI	H28				
N/A	TDO	H7				
N/A	TMS	K10				
N/A	PWRDWN_B	AF9				
N/A	HSWAP_EN	K25				
N/A	RSVD	G8				
N/A	VBATT	K9				
N/A	DXP	K26				
N/A	DXN	G27				
N/A	AVCCAUXTX2	B32	NC	NC		
N/A	VTTXPAD2	B33	NC	NC		
N/A	TXNPAD2	A33	NC	NC		
N/A	TXPPAD2	A32	NC	NC		
N/A	GNDA2	C30	NC	NC		
N/A	RXPPAD2	A31	NC	NC		
N/A	RXNPAD2	A30	NC	NC		
N/A	VTRXPAD2	B31	NC	NC		
N/A	AVCCAUXRX2	B30	NC	NC		
N/A	AVCCAUXTX4	B28				
N/A	VTTXPAD4	B29				
N/A	TXNPAD4	A29				
N/A	TXPPAD4	A28				
N/A	GNDA4	C27				
N/A	RXPPAD4	A27				
N/A	RXNPAD4	A26				
N/A	VTRXPAD4	B27				
N/A	AVCCAUXRX4	B26				
N/A	AVCCAUXTX5	B24	NC	NC	NC	

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
N/A	TXPPAD17	AP12	NC	NC	NC	
N/A	TXNPAD17	AP13	NC	NC	NC	
N/A	VTTXPAD17	AN13	NC	NC	NC	
N/A	AVCCAUXTX17	AN12	NC	NC	NC	
N/A	AVCCAUXRX18	AN14				
N/A	VTRXPAD18	AN15				
N/A	RXNPAD18	AP14				
N/A	RXPPAD18	AP15				
N/A	GNDA18	AM15				
N/A	TXPPAD18	AP16				
N/A	TXNPAD18	AP17				
N/A	VTTXPAD18	AN17				
N/A	AVCCAUXTX18	AN16				
N/A	AVCCAUXRX19	AN18				
N/A	VTRXPAD19	AN19				
N/A	RXNPAD19	AP18				
N/A	RXPPAD19	AP19				
N/A	GNDA19	AM20				
N/A	TXPPAD19	AP20				
N/A	TXNPAD19	AP21				
N/A	VTTXPAD19	AN21				
N/A	AVCCAUXTX19	AN20				
N/A	AVCCAUXRX20	AN22	NC	NC	NC	
N/A	VTRXPAD20	AN23	NC	NC	NC	
N/A	RXNPAD20	AP22	NC	NC	NC	
N/A	RXPPAD20	AP23	NC	NC	NC	
N/A	GNDA20	AM23	NC	NC	NC	
N/A	TXPPAD20	AP24	NC	NC	NC	
N/A	TXNPAD20	AP25	NC	NC	NC	
N/A	VTTXPAD20	AN25	NC	NC	NC	
N/A	AVCCAUXTX20	AN24	NC	NC	NC	
N/A	AVCCAUXRX21	AN26				
N/A	VTRXPAD21	AN27				
N/A	RXNPAD21	AP26				
N/A	RXPPAD21	AP27				
N/A	GNDA21	AM27				
N/A	TXPPAD21	AP28				
N/A	TXNPAD21	AP29				

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L02P_2	D9		
2	IO_L03N_2	B7		
2	IO_L03P_2	A7		
2	IO_L04N_2/VREF_2	B6		
2	IO_L04P_2	A6		
2	IO_L05N_2	E8		
2	IO_L05P_2	D8		
2	IO_L06N_2	B4		
2	IO_L06P_2	A4		
2	IO_L07N_2	B3		
2	IO_L07P_2	A3		
2	IO_L08N_2	H7		
2	IO_L08P_2	H8		
2	IO_L09N_2	C6		
2	IO_L09P_2	C7		
2	IO_L10N_2/VREF_2	C5		
2	IO_L10P_2	B5		
2	IO_L11N_2	K8		
2	IO_L11P_2	J8		
2	IO_L12N_2	C1		
2	IO_L12P_2	C2		
2	IO_L13N_2	E7		
2	IO_L13P_2	D7		
2	IO_L14N_2	J6		
2	IO_L14P_2	J7		
2	IO_L15N_2	D5		
2	IO_L15P_2	D6		
2	IO_L16N_2/VREF_2	E4		
2	IO_L16P_2	D4		
2	IO_L17N_2	L9		
2	IO_L17P_2	K9		
2	IO_L18N_2	E3		
2	IO_L18P_2	D3		
2	IO_L19N_2	D1		
2	IO_L19P_2	D2		
2	IO_L20N_2	K7		
2	IO_L20P_2	L7		
2	IO_L21N_2	F6		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
3	IO_L17N_3	AH9		
3	IO_L17P_3	AJ9		
3	IO_L16N_3	AK7		
3	IO_L16P_3	AL7		
3	IO_L15N_3/VREF_3	AK4		
3	IO_L15P_3	AL4		
3	IO_L14N_3	AJ7		
3	IO_L14P_3	AJ8		
3	IO_L13N_3	AK3		
3	IO_L13P_3	AL3		
3	IO_L12N_3	AL5		
3	IO_L12P_3	AL6		
3	IO_L11N_3	AK8		
3	IO_L11P_3	AL8		
3	IO_L10N_3	AL1		
3	IO_L10P_3	AL2		
3	IO_L09N_3/VREF_3	AM6		
3	IO_L09P_3	AM7		
3	IO_L08N_3	AL9		
3	IO_L08P_3	AM9		
3	IO_L07N_3	AM5		
3	IO_L07P_3	AN5		
3	IO_L06N_3	AM1		
3	IO_L06P_3	AM2		
3	IO_L05N_3	AN8		
3	IO_L05P_3	AN9		
3	IO_L04N_3	AN6		
3	IO_L04P_3	AP6		
3	IO_L03N_3/VREF_3	AN4		
3	IO_L03P_3	AP4		
3	IO_L02N_3	AN7		
3	IO_L02P_3	AP7		
3	IO_L01N_3/VRP_3	AN3		
3	IO_L01P_3/VRN_3	AP3		
4	IO_L01N_4/BUSY/DOUT(1)	AK10		
4	IO_L01P_4/INIT_B	AJ10		
4	IO_L02N_4/D0/DIN(1)	AF11		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
3	IO_L90P_3	AA8		
3	IO_L89N_3	Y11		
3	IO_L89P_3	Y12		
3	IO_L88N_3	AA5		
3	IO_L88P_3	AA6		
3	IO_L87N_3/VREF_3	AA3		
3	IO_L87P_3	AA4		
3	IO_L86N_3	Y13		
3	IO_L86P_3	AA13		
3	IO_L85N_3	AB7		
3	IO_L85P_3	AB8		
3	IO_L60N_3	AB5		
3	IO_L60P_3	AB6		
3	IO_L59N_3	AA9		
3	IO_L59P_3	AA10		
3	IO_L58N_3	AB3		
3	IO_L58P_3	AB4		
3	IO_L57N_3/VREF_3	AB1		
3	IO_L57P_3	AB2		
3	IO_L56N_3	AA11		
3	IO_L56P_3	AA12		
3	IO_L55N_3	AC5		
3	IO_L55P_3	AC6		
3	IO_L54N_3	AC1		
3	IO_L54P_3	AC2		
3	IO_L53N_3	AB9		
3	IO_L53P_3	AB10		
3	IO_L52N_3	AC8		
3	IO_L52P_3	AD8		
3	IO_L51N_3/VREF_3	AC4		
3	IO_L51P_3	AD4		
3	IO_L50N_3	AB11		
3	IO_L50P_3	AB12		
3	IO_L49N_3	AD6		
3	IO_L49P_3	AD7		
3	IO_L48N_3	AD2		
3	IO_L48P_3	AD3		
3	IO_L47N_3	AC9		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
7	IO_L24N_7	L37		
7	IO_L23P_7	P31		
7	IO_L23N_7	P32		
7	IO_L22P_7	L34		
7	IO_L22N_7/VREF_7	L35		
7	IO_L21P_7	L32		
7	IO_L21N_7	L33		
7	IO_L20P_7	N29		
7	IO_L20N_7	M29		
7	IO_L19P_7	K38		
7	IO_L19N_7	K39		
7	IO_L18P_7	J37		
7	IO_L18N_7	K37		
7	IO_L17P_7	N30		
7	IO_L17N_7	P30		
7	IO_L16P_7	K35		
7	IO_L16N_7/VREF_7	K36		
7	IO_L15P_7	K34		
7	IO_L15N_7	K33		
7	IO_L14P_7	N31		
7	IO_L14N_7	M32		
7	IO_L13P_7	J38		
7	IO_L13N_7	J39		
7	IO_L12P_7	J35		
7	IO_L12N_7	H36		
7	IO_L11P_7	M30		
7	IO_L11N_7	L31		
7	IO_L10P_7	J33		
7	IO_L10N_7/VREF_7	J34		
7	IO_L09P_7	H37		
7	IO_L09N_7	H38		
7	IO_L08P_7	K31		
7	IO_L08N_7	K32		
7	IO_L07P_7	H33		
7	IO_L07N_7	H34		
7	IO_L84P_7	G38	NC	
7	IO_L84N_7	G39	NC	
7	IO_L82P_7	G36	NC	

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
7	IO_L82N_7/VREF_7	G37	NC	
7	IO_L81P_7	G33	NC	
7	IO_L81N_7	G34	NC	
7	IO_L79P_7	F38	NC	
7	IO_L79N_7	F39	NC	
7	IO_L78P_7	F36	NC	
7	IO_L78N_7	F37	NC	
7	IO_L76P_7	G35	NC	
7	IO_L76N_7/VREF_7	F35	NC	
7	IO_L75P_7	E37	NC	
7	IO_L75N_7	E38	NC	
7	IO_L73P_7	D38	NC	
7	IO_L73N_7	D39	NC	
7	IO_L06P_7	F33		
7	IO_L06N_7	E33		
7	IO_L05P_7	J31		
7	IO_L05N_7	H32		
7	IO_L04P_7	E34		
7	IO_L04N_7/VREF_7	D34		
7	IO_L03P_7	D35		
7	IO_L03N_7	C35		
7	IO_L02P_7	H31		
7	IO_L02N_7	G31		
7	IO_L01P_7/VRN_7	D33		
7	IO_L01N_7/VRP_7	C33		
7	VCCO_7	E39		
7	VCCO_7	U37		
7	VCCO_7	N36		
7	VCCO_7	J36		
7	VCCO_7	E36		
7	VCCO_7	Y35		
7	VCCO_7	U33		
7	VCCO_7	N32		
7	VCCO_7	J32		
7	VCCO_7	F32		
7	VCCO_7	U29		
7	VCCO_7	N28		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
6	IO_L34N_6		AH38		
6	IO_L35P_6		AH31		
6	IO_L35N_6		AH32		
6	IO_L36P_6		AJ40		
6	IO_L36N_6		AH40		
6	IO_L37P_6		AH41		
6	IO_L37N_6		AH42		
6	IO_L38P_6		AH35		
6	IO_L38N_6		AG35		
6	IO_L39P_6		AG36		
6	IO_L39N_6/VREF_6		AG37		
6	IO_L40P_6		AG38		
6	IO_L40N_6		AG39		
6	IO_L41P_6		AG32		
6	IO_L41N_6		AG33		
6	IO_L42P_6		AG40		
6	IO_L42N_6		AG41		
6	IO_L43P_6		AF33		
6	IO_L43N_6		AF34		
6	IO_L44P_6		AF35		
6	IO_L44N_6		AF36		
6	IO_L45P_6		AF37		
6	IO_L45N_6/VREF_6		AF38		
6	IO_L46P_6		AF39		
6	IO_L46N_6		AF40		
6	IO_L47P_6		AF31		
6	IO_L47N_6		AG31		
6	IO_L48P_6		AF41		
6	IO_L48N_6		AF42		
6	IO_L49P_6		AE35		
6	IO_L49N_6		AE36		
6	IO_L50P_6		AE31		
6	IO_L50N_6		AF32		
6	IO_L51P_6		AE38		
6	IO_L51N_6/VREF_6		AE39		
6	IO_L52P_6		AE41		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L03P_7		D37		
7	IO_L03N_7		E37		
7	IO_L02P_7		D36		
7	IO_L02N_7		E36		
7	IO_L01P_7/VRN_7		C37		
7	IO_L01N_7/VRP_7		C38		
0	VCCO_0		D25		
0	VCCO_0		G23		
0	VCCO_0		G28		
0	VCCO_0		G32		
0	VCCO_0		J25		
0	VCCO_0		J29		
0	VCCO_0		P22		
0	VCCO_0		P23		
0	VCCO_0		P24		
0	VCCO_0		P25		
0	VCCO_0		P26		
0	VCCO_0		R22		
0	VCCO_0		R23		
0	VCCO_0		R24		
0	VCCO_0		R25		
1	VCCO_1		R21		
1	VCCO_1		R20		
1	VCCO_1		R19		
1	VCCO_1		R18		
1	VCCO_1		P21		
1	VCCO_1		P20		
1	VCCO_1		P19		
1	VCCO_1		P18		
1	VCCO_1		P17		
1	VCCO_1		J18		
1	VCCO_1		J14		
1	VCCO_1		G20		
1	VCCO_1		G15		
1	VCCO_1		G11		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L62N_6	AL35	
6	IO_L63P_6	AV36	
6	IO_L63N_6/VREF_6	AU36	
6	IO_L64P_6	AV35	
6	IO_L64N_6	AU35	
6	IO_L65P_6	AK35	
6	IO_L65N_6	AJ34	
6	IO_L66P_6	AU41	
6	IO_L66N_6	AU42	
6	IO_L67P_6	AU38	
6	IO_L67N_6	AT38	
6	IO_L68P_6	AK32	
6	IO_L68N_6	AK33	
6	IO_L69P_6	AU37	
6	IO_L69N_6/VREF_6	AT37	
6	IO_L70P_6	AT41	
6	IO_L70N_6	AT42	
6	IO_L71P_6	AK31	
6	IO_L71N_6	AJ31	
6	IO_L72P_6	AT39	
6	IO_L72N_6	AT40	
6	IO_L07P_6	AT35	
6	IO_L07N_6	AT36	
6	IO_L08P_6	AJ32	
6	IO_L08N_6	AJ33	
6	IO_L09P_6	AR42	
6	IO_L09N_6/VREF_6	AP41	
6	IO_L10P_6	AR40	
6	IO_L10N_6	AR41	
6	IO_L11P_6	AH34	
6	IO_L11N_6	AH35	
6	IO_L12P_6	AR38	
6	IO_L12N_6	AR39	
6	IO_L13P_6	AR36	
6	IO_L13N_6	AR37	
6	IO_L14P_6	AH32	
6	IO_L14N_6	AH33	